

FIG. 1

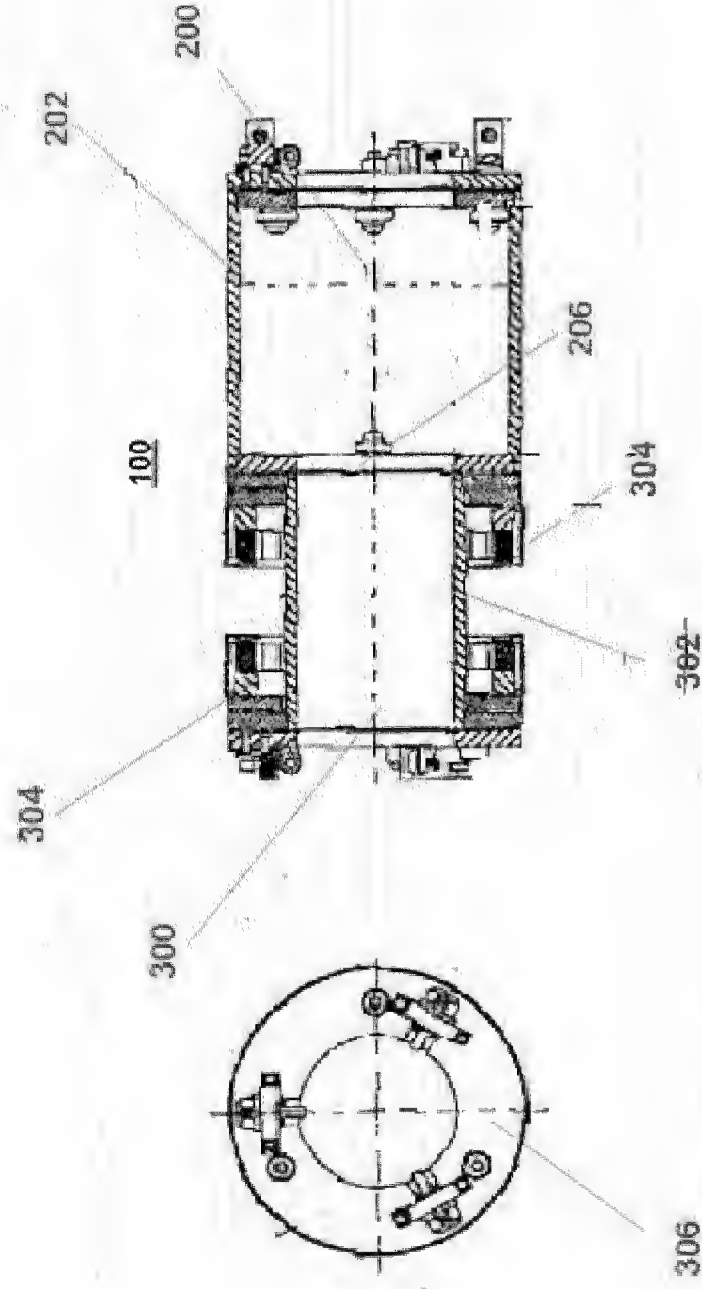


FIG. 2A

FIG. 2B

FIG. 2C

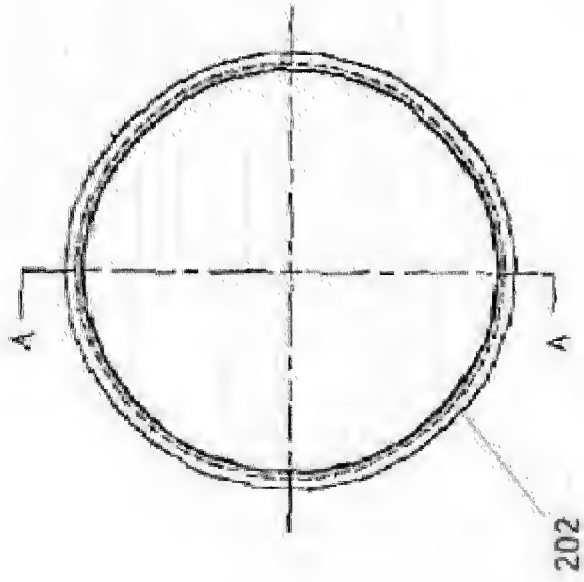
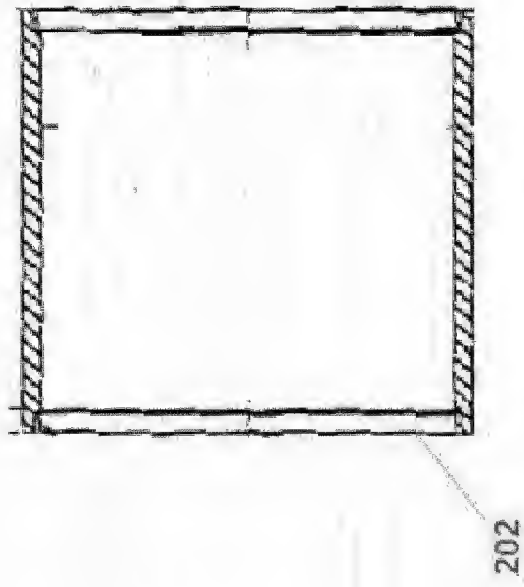


FIG. 3A



SECTION A-A

FIG. 3B

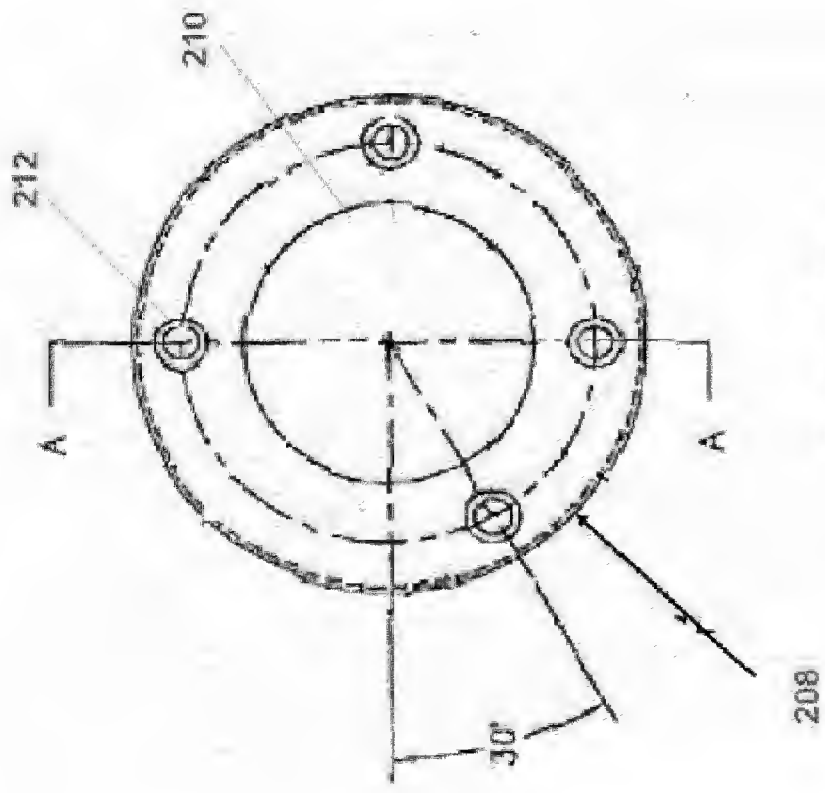


FIG. 4A

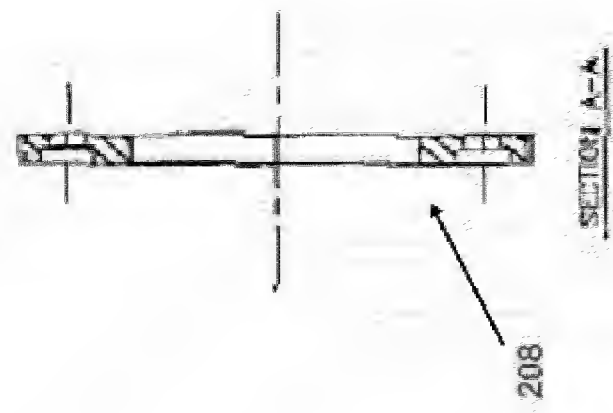


FIG. 4B

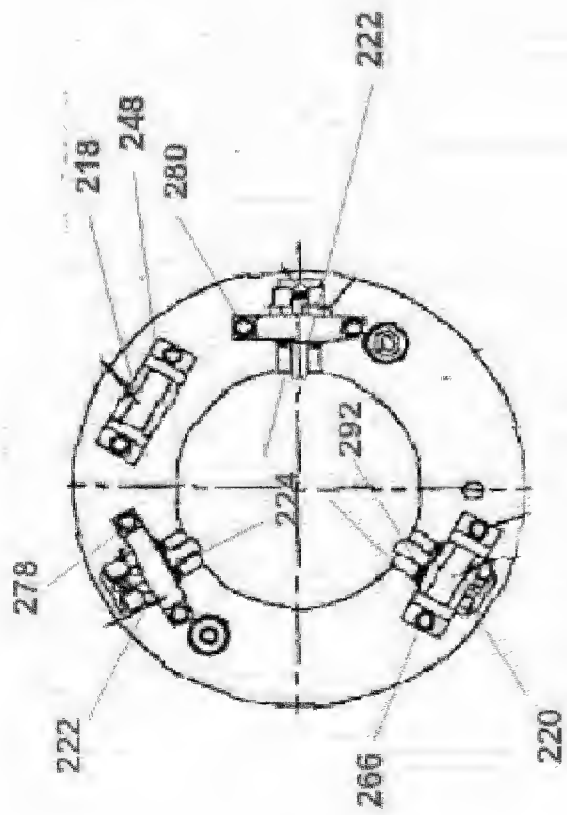


FIG. 5A

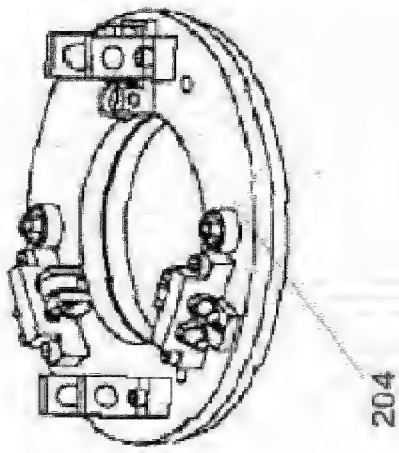


FIG. 5C

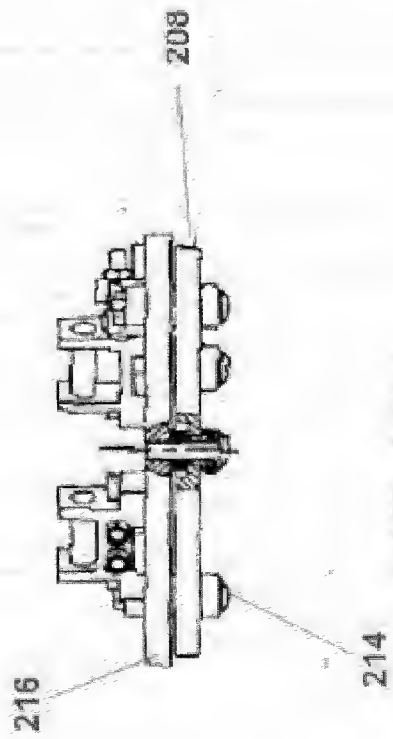


FIG. 5B

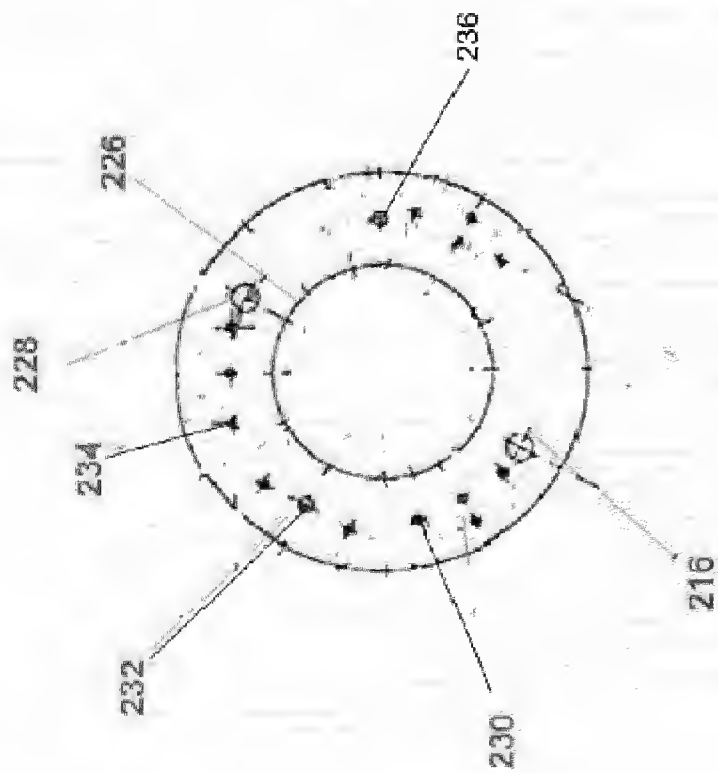


FIG. 6A

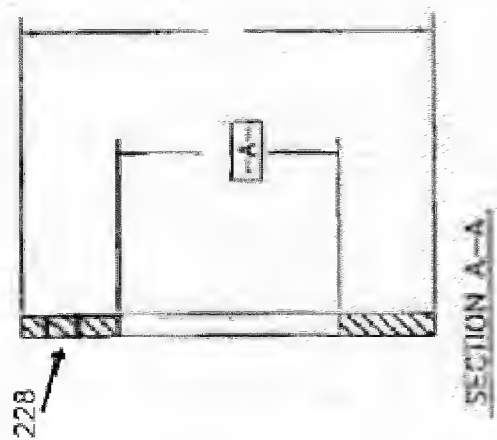


FIG. 6B

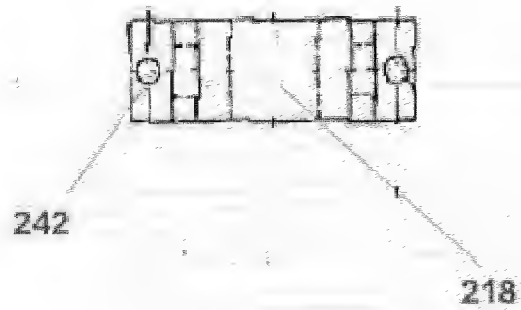


FIG. 7A

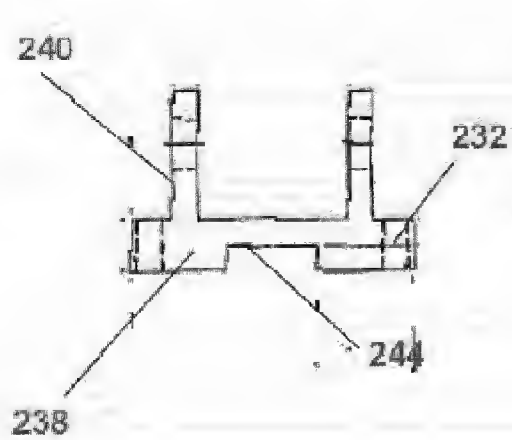


FIG. 7B



FIG. 7C

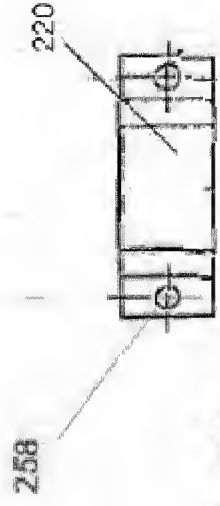


FIG. 8A

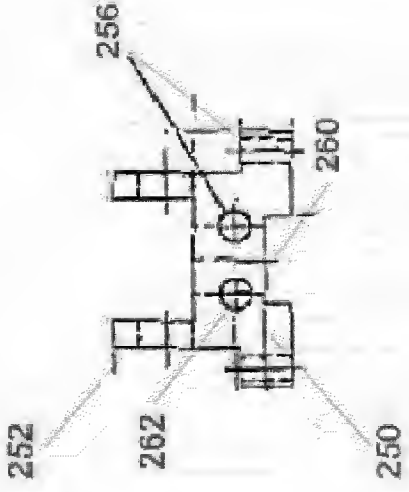


FIG. 8B

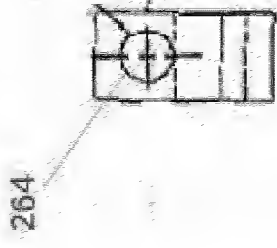


FIG. 8C

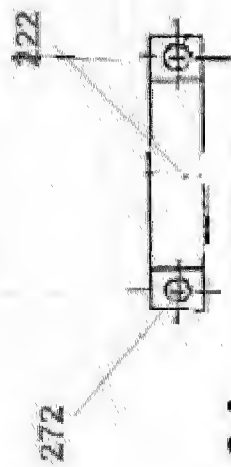


FIG. 9A

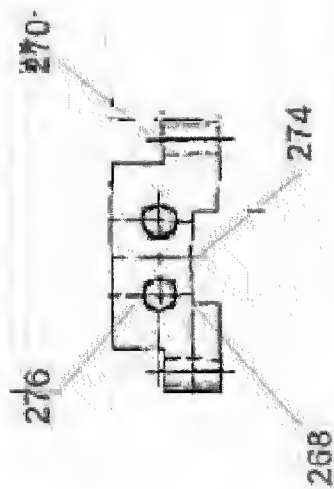


FIG. 9B



FIG. 9C

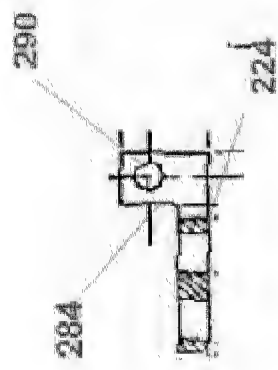


FIG. 10A

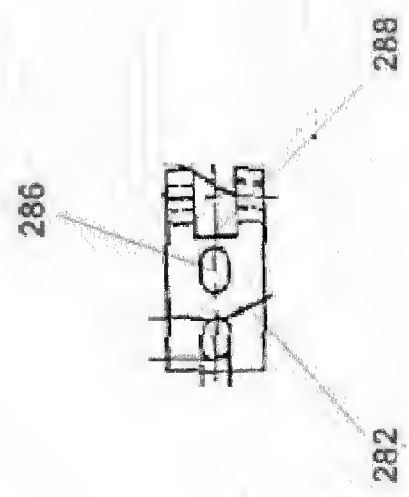


FIG. 10B

294



292

FIG. 11A



292

FIG. 11B

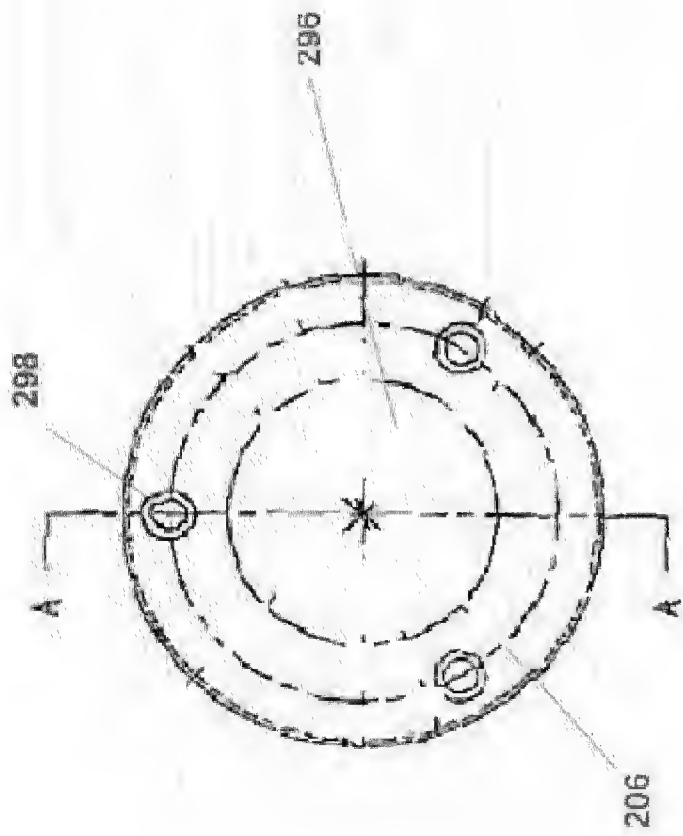


FIG. 12A

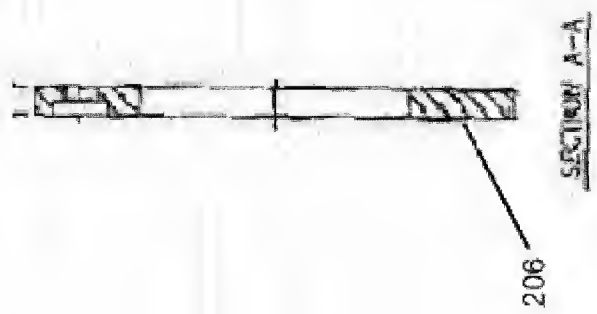


FIG. 12B

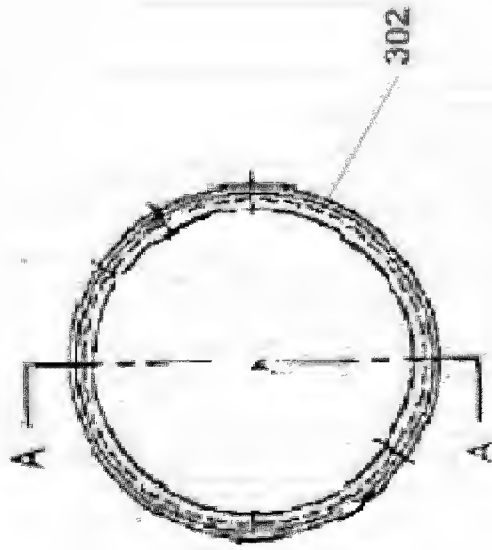
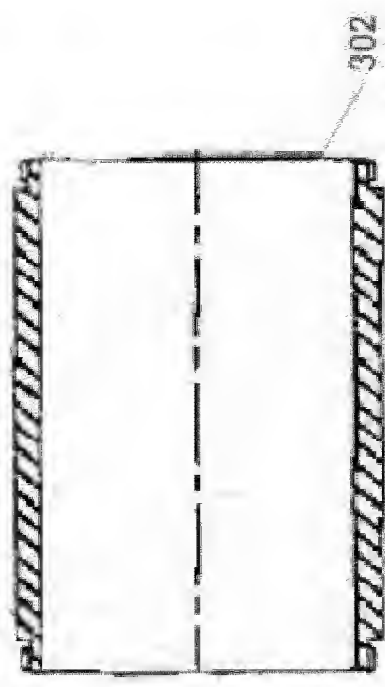


FIG. 13A



SECTION A-A

FIG. 13B

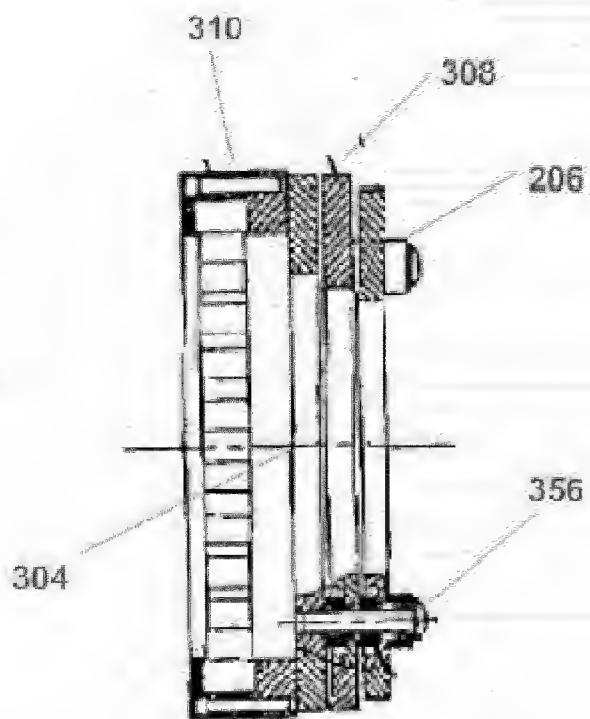


FIG. 14

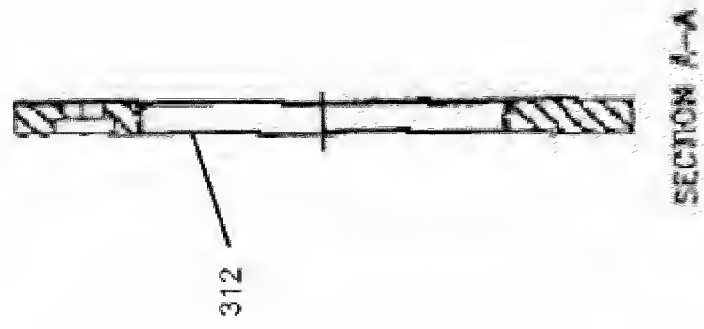
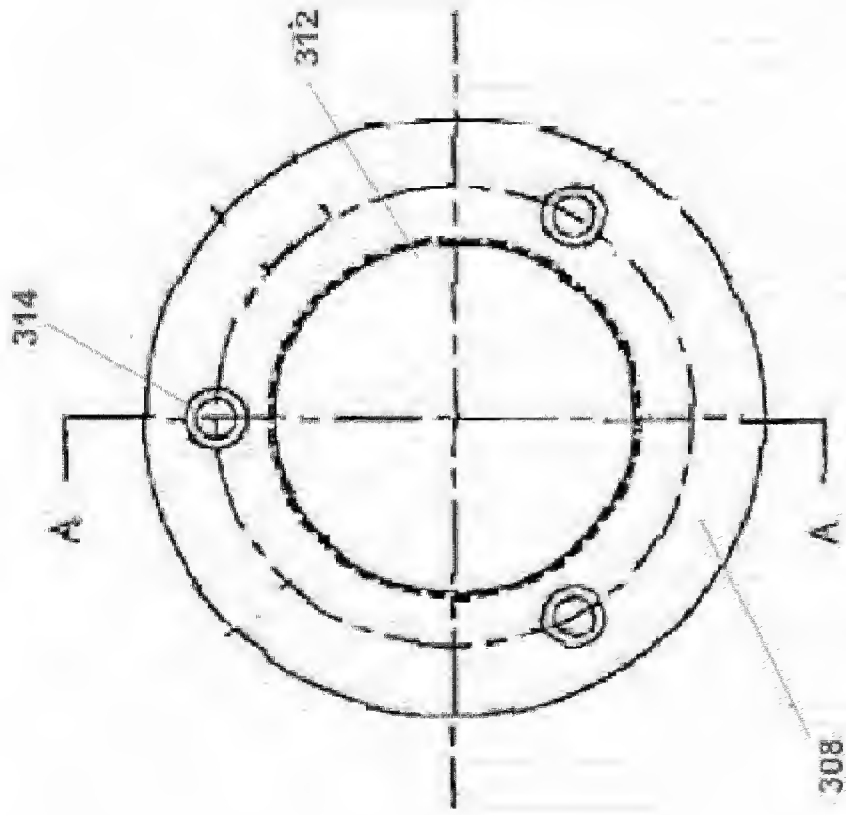


FIG. 15A

FIG. 15B

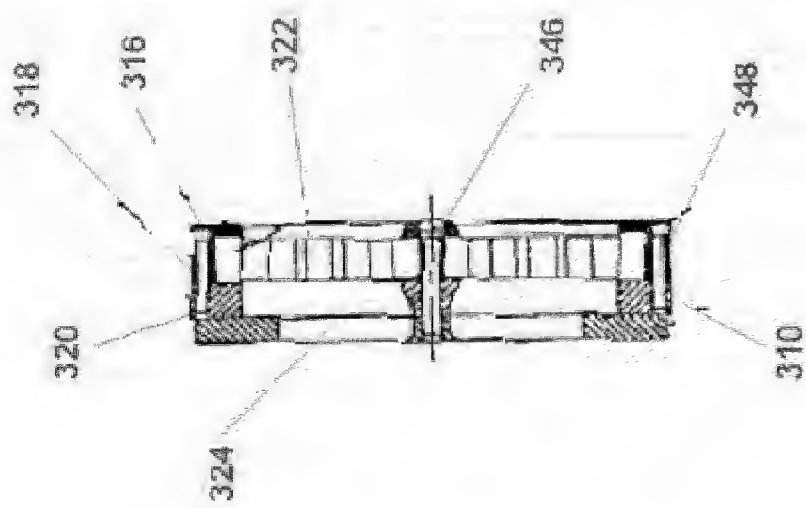


FIG 16A

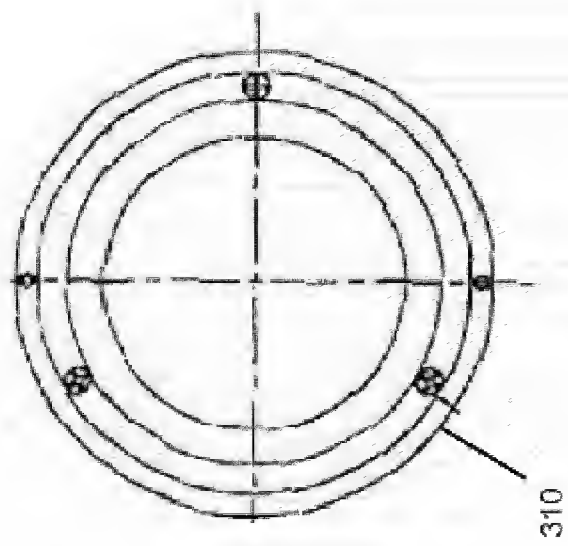


FIG. 16B

328



SECTION A-A

FIG. 17B

330



SECTION B-B

FIG. 17C

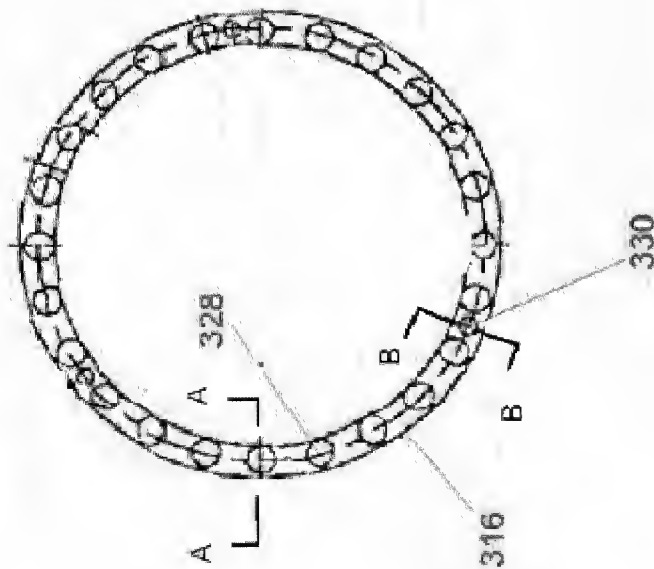
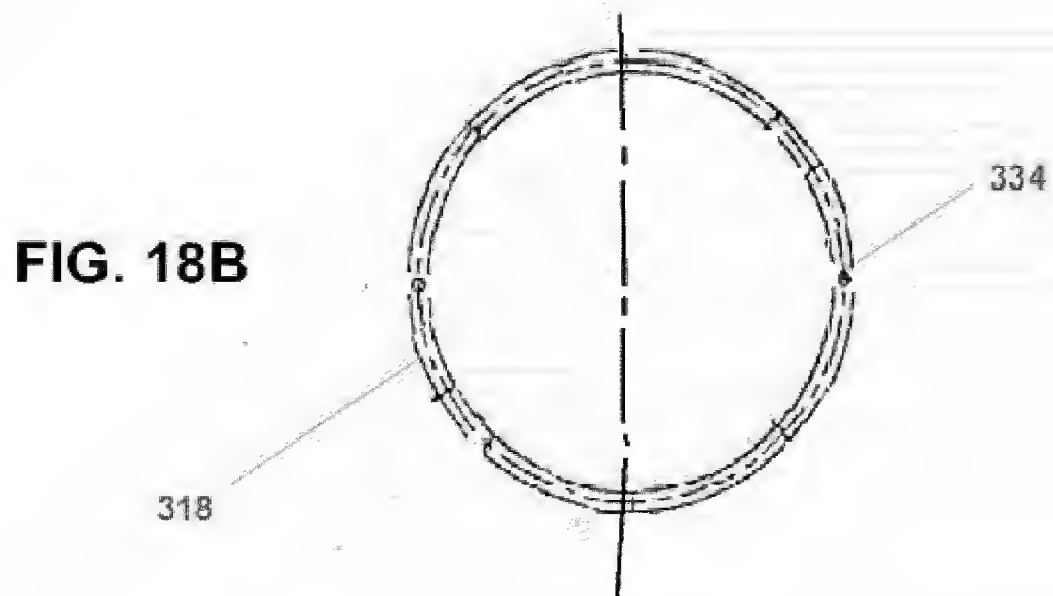


FIG. 17A



FIG. 18A



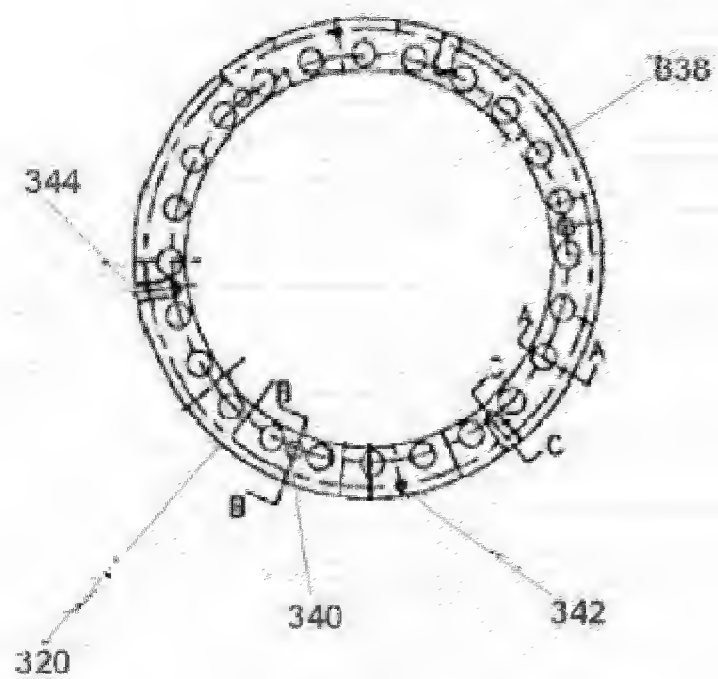


FIG. 19

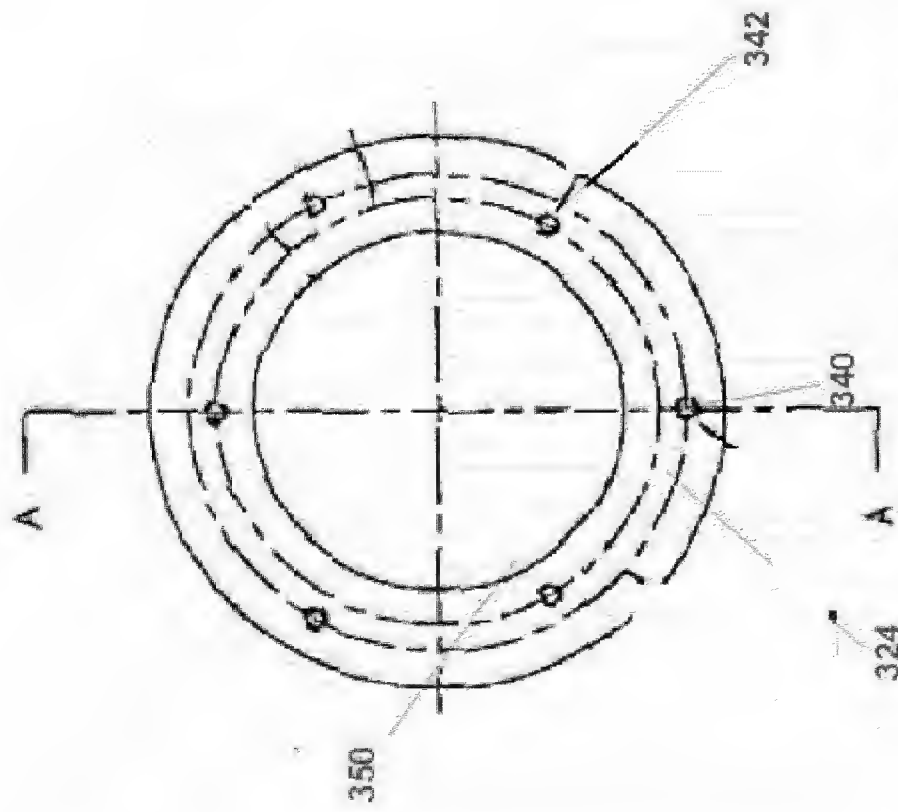


FIG. 20A

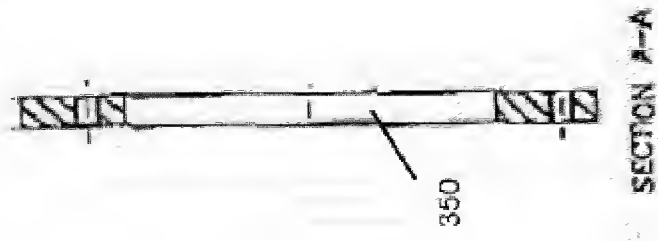


FIG. 20B

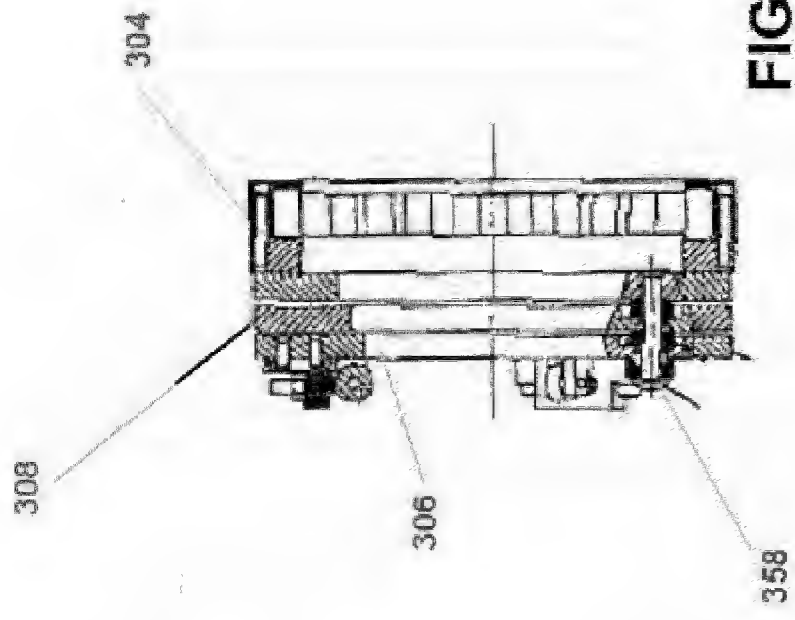


FIG. 21B

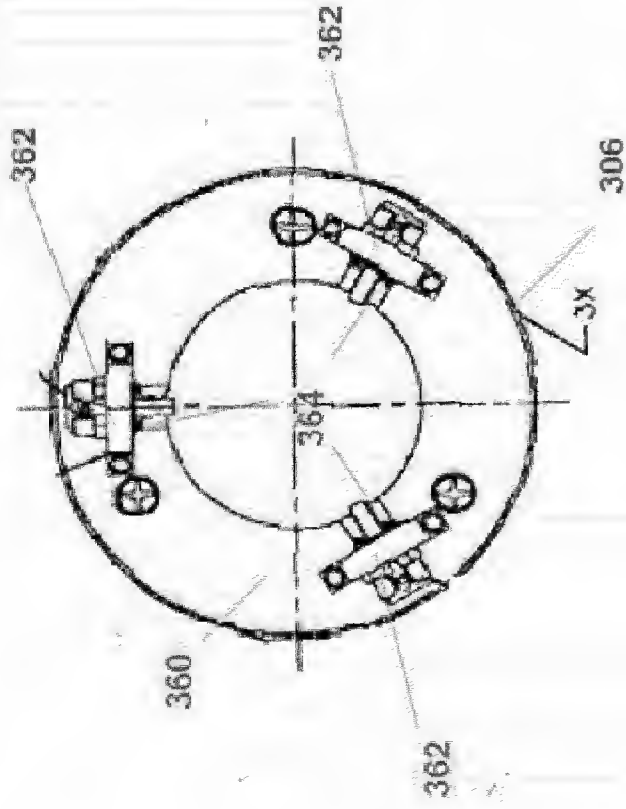


FIG. 21A

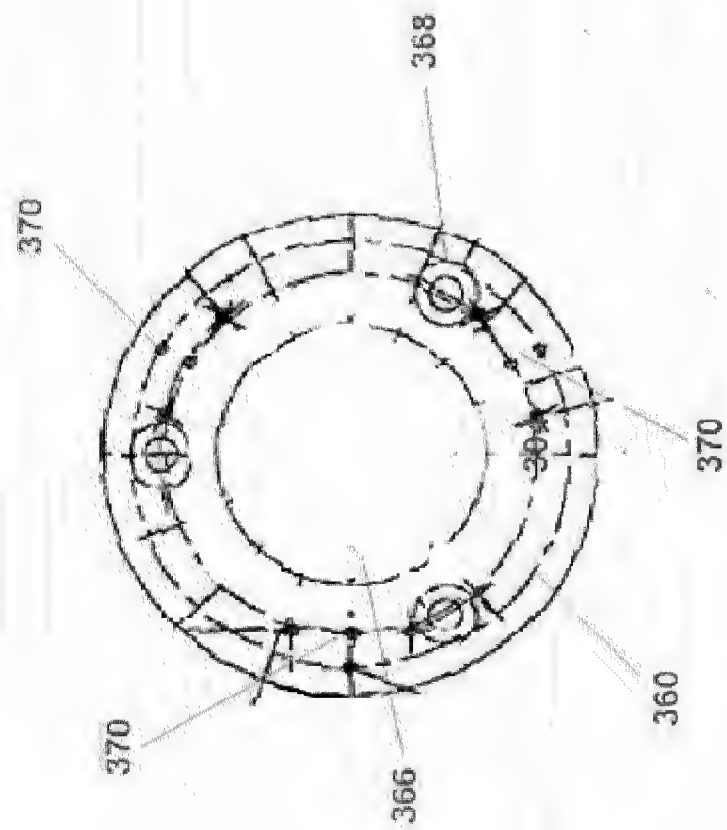


FIG. 22A



SECTION A-A

FIG. 22B

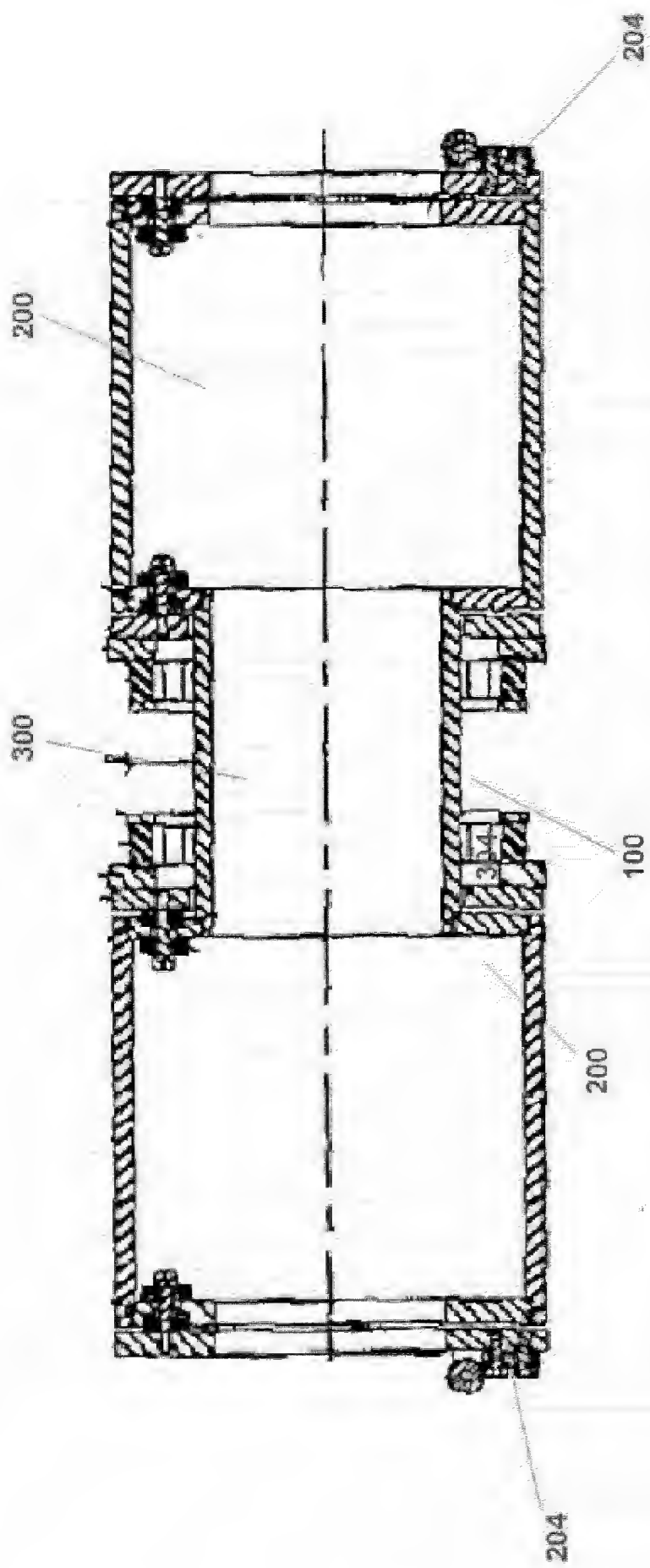
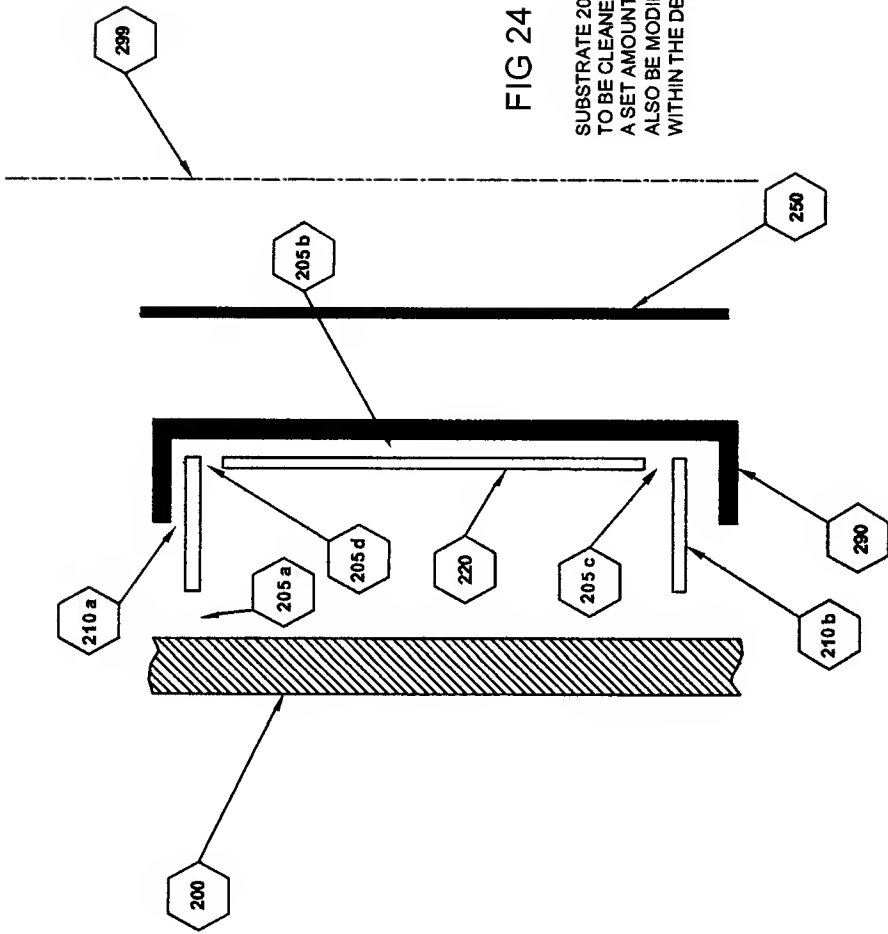


FIG. 23



SUBSTRATE 200 AND TARGET 250 ARE SURFACES TO BE CLEANED OF RESIDUAL CONTAMINATION OR A SET AMOUNT OF MATERIAL DEPTH. SURFACES CAN ALSO BE MODIFIED BY A PROCESS THAT IS CONTAINED WITHIN THE DEVICE.

FIG 24

FIG 25

IS A CROSS SECTIONAL
VIEW OF THE PLASMA CLEANING
AND COLLECTION DEVICE
COMPRISING OF AN INTERNALLY
GENERATED MAGNETIC FIELD.

THE COLLECTION SURFACE IS
NUMBERED: 320, 310 a, AND 320 b.

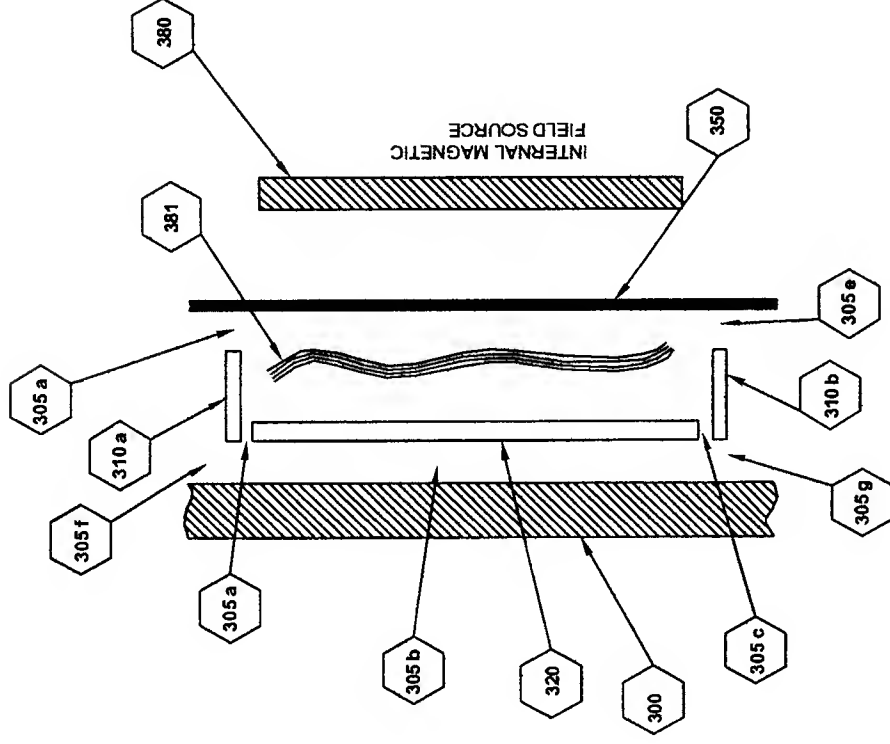


FIG 25

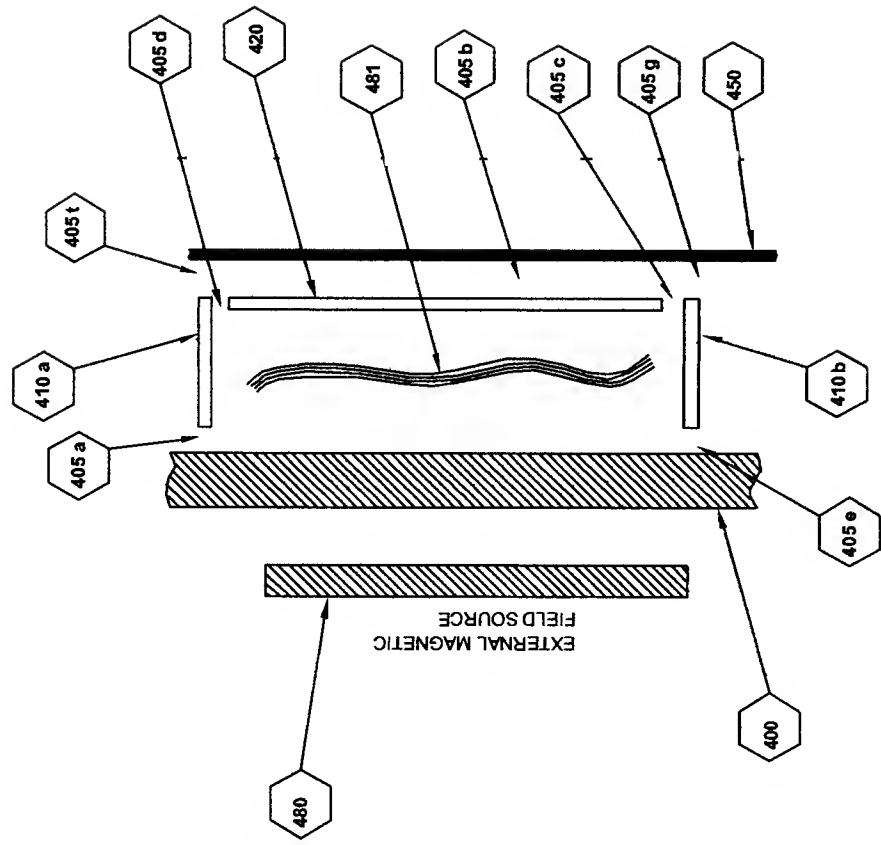
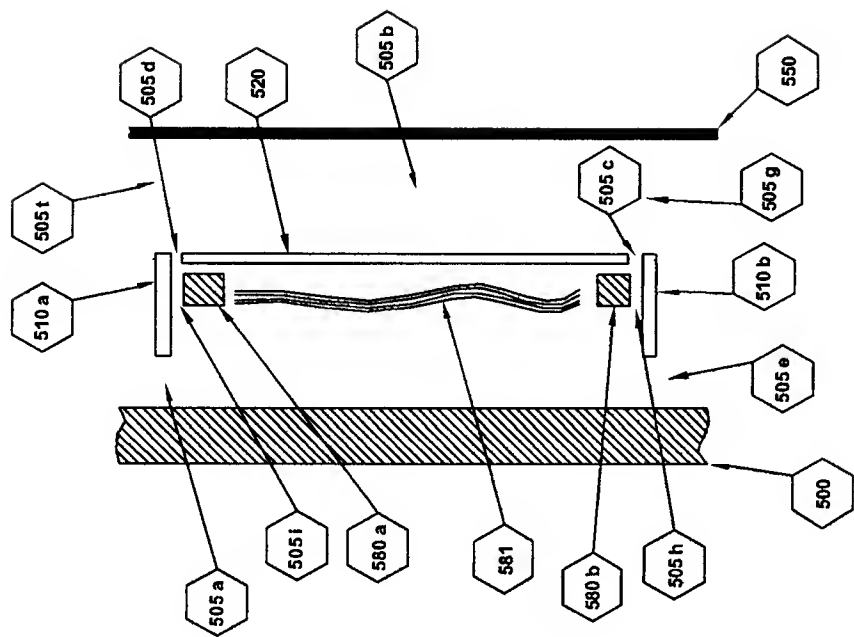


FIG 26



**MAGNETIC FIELD SOURCE ON DEVICE
LOCATED WITHIN HOUSING**

FIG 27